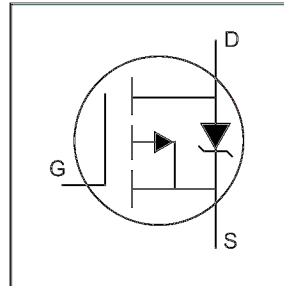


- Ultra Low On-Resistance
- P-Channel
- Surface Mount (IRFR9120N)
- Straight Lead (IRFU9120N)
- Advanced Process Technology
- Fast Switching
- Fully Avalanche Rated
- Lead-Free



$$V_{DSS} = -100V$$

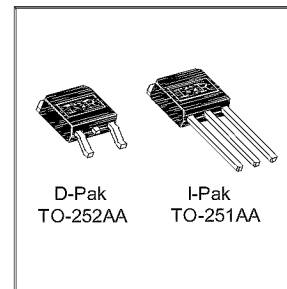
$$R_{DS(on)} = 0.48\Omega$$

$$I_D = -6.6A$$

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The D-Pak is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead version (IRFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.



D-Pak
TO-252AA

I-Pak
TO-251AA

Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-6.6	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-4.2	
I_{DM}	Pulsed Drain Current $\text{\textcircled{D}}$	-26	
$P_D @ T_C = 25^\circ C$	Power Dissipation	40	W
	Linear Derating Factor	0.32	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy $\text{\textcircled{D}}$	100	mJ
I_{AR}	Avalanche Current $\text{\textcircled{D}}$	-6.6	A
E_{AR}	Repetitive Avalanche Energy $\text{\textcircled{D}}$	4.0	mJ
dv/dt	Peak Diode Recovery dv/dt $\text{\textcircled{D}}$	-5.0	V/ns
T_J	Operating Junction and	-55 to + 150	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Thermal Resistance

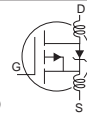
	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	---	3.1	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB mount)**	---	50	
$R_{\theta JA}$	Junction-to-Ambient	---	110	

IRFR/U9120NPbF

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-100	—	—	V	$V_{GS} = 0\text{V}$, $I_D = -250\mu\text{A}$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.11	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = -1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.48	Ω	$V_{GS} = -10\text{V}$, $I_D = -3.9\text{A}$ ④
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$V_{DS} = V_{GS}$, $I_D = -250\mu\text{A}$
g_{fs}	Forward Transconductance	1.4	—	—	S	$V_{DS} = -50\text{V}$, $I_D = -4.0\text{A}$ ⑥
I_{DSS}	Drain-to-Source Leakage Current	—	—	-25	μA	$V_{DS} = -100\text{V}$, $V_{GS} = 0\text{V}$ $V_{DS} = -80\text{V}$, $V_{GS} = 0\text{V}$, $T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100	nA	$V_{GS} = -20\text{V}$
Q_g	Total Gate Charge	—	—	27	nC	$I_D = -4.0\text{A}$ $V_{DS} = -80\text{V}$ $V_{GS} = -10\text{V}$, See Fig. 6 and 13 ④ ⑥
Q_{gs}	Gate-to-Source Charge	—	—	5.0	nC	
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	15	nC	
$t_{d(on)}$	Turn-On Delay Time	—	14	—	ns	$V_{DD} = -50\text{V}$ $I_D = -4.0\text{A}$ $R_G = 12\ \Omega$ $R_D = 12\ \Omega$, See Fig. 10 ④ ⑥
t_r	Rise Time	—	47	—		
$t_{d(off)}$	Turn-Off Delay Time	—	28	—		
t_f	Fall Time	—	31	—		
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact ⑤
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	350	—	pF	$V_{GS} = 0\text{V}$ $V_{DS} = -25\text{V}$ $f = 1.0\text{MHz}$, See Fig. 5 ⑥
C_{oss}	Output Capacitance	—	110	—		
C_{riss}	Reverse Transfer Capacitance	—	70	—		



Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-6.6	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	-26		
V_{SD}	Diode Forward Voltage	—	—	-1.6	V	$T_J = 25^\circ\text{C}$, $I_S = -3.9\text{A}$, $V_{GS} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	100	150	ns	$T_J = 25^\circ\text{C}$, $I_F = -4.0\text{A}$
Q_{rr}	Reverse Recovery Charge	—	420	630	nC	$di/dt = 100\text{A}/\mu\text{s}$ ④ ⑥
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting $T_J = 25^\circ\text{C}$, $L = 13\text{mH}$
 $R_G = 25\ \Omega$, $I_{AS} = -3.9\text{A}$. (See Figure 12)
- ③ $I_{SD} \leq -4.0\text{A}$, $di/dt \leq 300\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$,
 $T_J \leq 150^\circ\text{C}$
- ④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑤ This is applied for I-PAK, L_S of D-PAK is measured between lead and center of die contact
- ⑥ Uses IRF9520N data and test conditions.

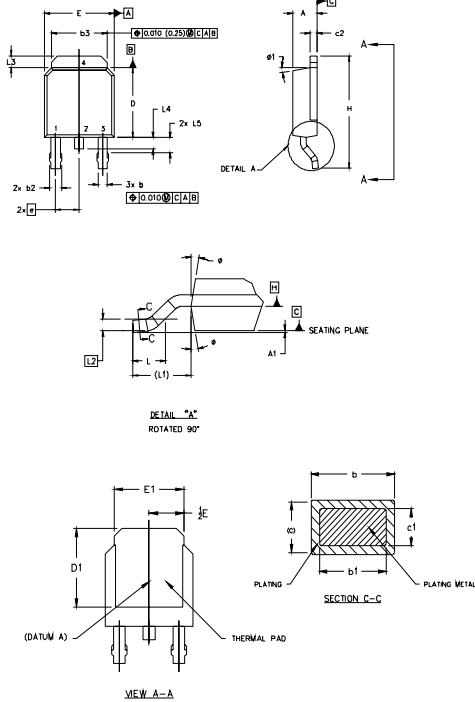
** When mounted on 1" square PCB (FR-4 or G-10 Material) .
For recommended footprint and soldering techniques refer to application note #AN-994

IRFR/U9120NPbF

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D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M-1994.
- 2.0 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- 3.0 LEAD DIMENSION UNCONTROLLED IN L5.
- 4.0 DIMENSION D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.0 SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 [0.127] AND .010 [0.254] FROM THE LEAD TIP.
- 6.0 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .003" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 7.0 OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.30	.086	.094	
A1		0.13		.005	
b	0.64	0.89	.025	.035	5
b1	0.64	0.79	.025	0.031	5
b2	0.76	1.14	.030	.045	
b3	4.95	5.46	.195	.215	
c	0.46	0.61	.018	.024	5
c1	0.41	0.56	.016	.022	5
c2	.046	0.89	.018	.035	5
D	5.97	6.27	.235	.246	6
D1	5.21	-	.205	-	4
E	6.35	6.73	.250	.265	6
E1	4.32	-	.170	-	4
e	2.29		.090 BSC		
H	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2.74 REF.		.108 REF.		
L2	0.051 BSC		0.020 BSC		
L3	0.89	1.27	.035	.050	
L4		1.02		.040	
L5	1.14	1.52	.045	.060	
#	0"	10"	0"	10"	
#1	0"	15"	0"	15"	

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

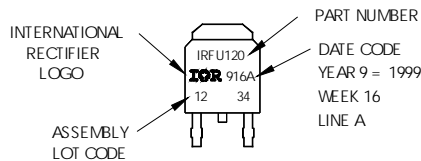
IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

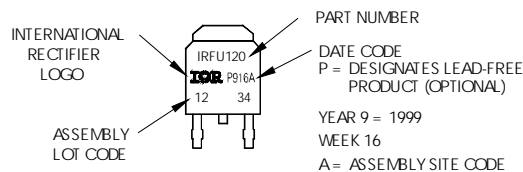
D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 1234
ASSEMBLED ON WW16, 1999
IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position
indicates "Lead-Free"



OR

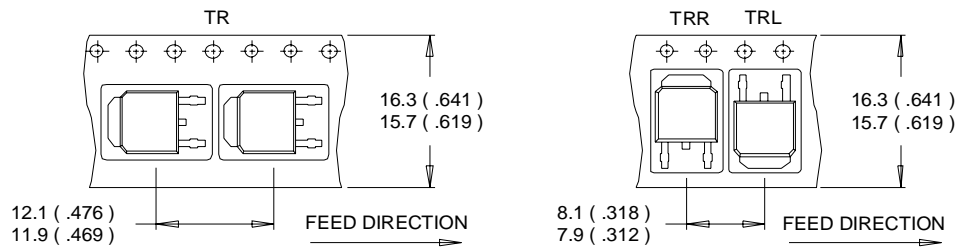


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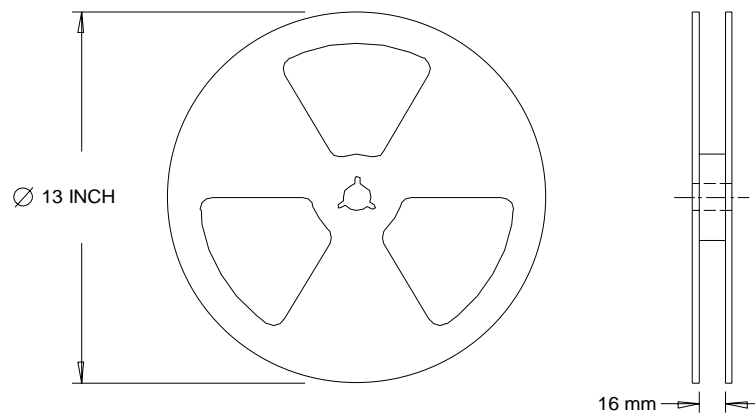
D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.

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